Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1-9. (Canceled).

10. (Previously Presented) A method for sealing an organic EL display panel having a multi-layered structure in which a first electrode and a second electrode are formed on a transparent panel and at least one organic EL layer is formed between them, the method for sealing an organic EL display panel comprising the steps of:

forming a buffer layer on the transparent panel; and

locating a shield cover on the buffer layer;

wherein the buffer layer is formed on an entire surface of the transparent panel other than a tap bonding region and a pixel region of the first and second electrodes.

11. (Canceled).

12. (Previously Presented) The method of claim 10 or 19, wherein the buffer layer is formed only on the panel in a region where the shield cover is located.

13. (Currently Amended) The method of claim 10 or 19, wherein the buffer layer is formed both on the panel in a region where the shield cover is located and on the first electrode in a region where the shield cover is located.

14. (Previously Presented) The method of claim 10 or 19, wherein the buffer layer in the region where the shield cover is located has an uneven shape or a dot shape.

15. (Original) The method of claim 14, wherein the dot shaped buffer layer is formed of any one of a round shape, a triangle shape, a quadrangle shape, and a polygonal shape.

16. (Previously Presented) The method of claim 10 or 19, wherein the buffer layer in the region where the shield cover is located and the buffer layer in a region other than the region where the shield cover is located have the same material as each other or a different material from each other.

17. (Previously Presented) The method of claim 16, wherein the material of the buffer layer in the region where the shield cover is located is either silicon oxide or silicon nitride, while the material of the buffer layer in the region other than the region where the shield cover is located is any one of silicon oxide, silicon nitride, polyimide, and polyacryl.

18. (Previously Presented) The method of claim 10 or 19, wherein the buffer layer has a thickness of about 0.1 ~ 5μm.

19. (Previously Presented) A method for sealing an organic EL display panel having a multi-layered structure, a first electrode and a second electrode formed on a transparent panel and an at least one organic EL layer formed between them, comprising the steps of:

forming a buffer layer on an entire surface of the transparent panel other than a tap bonding region and a pixel region of the first and second electrodes;

forming an organic EL layer on the pixel region of the first and second electrodes;

forming an adhesive layer on the buffer layer; and

forming a shield cover on the adhesive layer for protecting the organic EL layer.

20. (Canceled).